



Super
cost
saver

Model ID
PSX307

Model No. NM-EFP1A

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Model No.	NM-EFP1A
Cleaning Method	Parallel plate RF back-sputtering method
Gas for Electrical Discharge ^{*1}	Ar [option:O ₂]
Substrate Dimensions	L 50 mm X W 20 mm to L 250 mm X W 75 mm ^{*2} incl. S type option L 50 mm X W 20 mm to L 330 mm X W 120 mm incl. M type option
Substrate Thickness	0.5 mm to 2.0 mm
Dimensions / Mass ^{*3}	W 930 mm X D 1100 mm X H 1 450 mm / 555 kg W 1 764 mm X D 1 100 mm X H 1 450 mm / 850 kg incl. S type option W 1 764 mm X D 1 100 mm X H 1 450 mm / 770 kg incl. M type option
Power Source ^{*4}	1-phase AC 200 V, 2.00 kVA [Full Load 5.00 kVA]
Pneumatic Source	0.49 MPa or more, 6.5 L/min [A.N.R.]

*Please refer to the specifications on details.

*1: If the optional oxygen gas is selected as a discharge gas, nitrogen gas is also required to dilute exhaust.

*2: For W 70.1mm to W 75mm, the electrode in the chamber is required separately.

*3: Tolerance of equipment dimensions is ±5mm, Touch panel and condition lamp is not included. Mass varies depending on configuration.

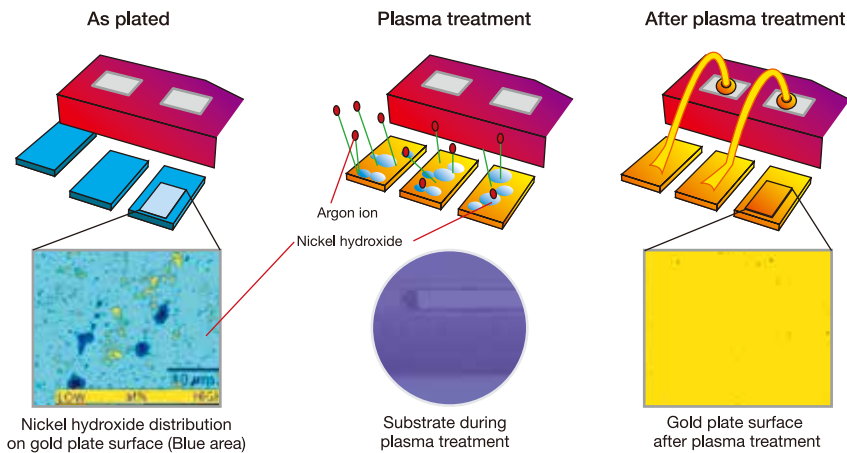
*4: Compatible with 1-phase 208/220/230/240 V

The reason why an extra-thin gold plated electrode can be used

When an extra-thin gold plated electrode is used, nickel compounds are formed on a surface after the heat treatment by the die-bonding cure. These nickel compounds impair the wire bonding performance, thus it is said that a thin gold plated electrode is unsuitable for wire bonding. However, the argon plasma treatment eliminates the nickel compounds, therefore stable wire bonding can be performed on an extra-thin and extra-cheap gold plated electrode.

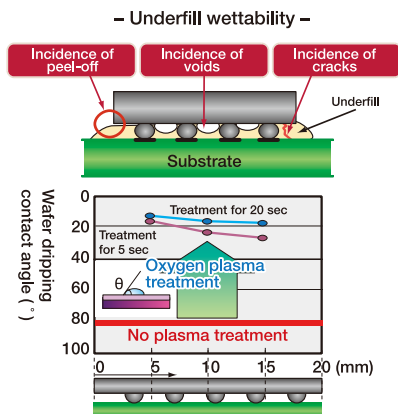
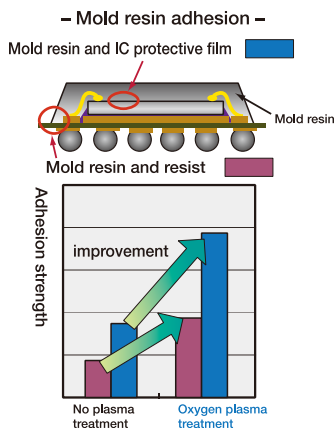
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Japanese patents 2 783 133, 2 783 260, 3 000 877
U.S.patents 5 647 942, 5 767 008, 6 331 347
U.K.patents 2 297 981
German patents 19 606 074



Surface reforming by oxygen plasma

Surface reforming by oxygen radical improves mold resin adhesion and under-fill wettability. (Option)



Transfer system options



M type
M type transfer system, loader, and unloader



S type
S type transfer system, loader, and unloader

⚠ Safety Cautions

- Please read the User's Manual carefully to familiarize yourself with safe and effective usage procedures.
- To ensure safety when using this equipment all work should be performed according to that as stated in the supplied Operating Instructions. Read your operating instruction manual thoroughly.

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ISO 14001 Panasonic Group builds Environmental Management System in the factories of the world and acquires the International Environmental Standard ISO 14001.

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